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TITLE: LQFP PACKAGE, 128 TERMINAL, 14X20X1.4, 0.5 PITCH EXPOSED PAD	DOCUMENT NO: 98ASA00098D	REV: A
	STANDARD: M026-BHB	
	SOT848-2	07 JAN 2016



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- △4. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
- △5. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 MM.
- △6. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
- △7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- △8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 MM AND 0.25 MM FROM THE LEAD TIP.
- △9. DISTANCE BETWEEN PACKAGE BODY AND EVERY LEAD TIP SHALL BE MAINTAINED AT MINIMUM 0.03MM.

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